



Docket No: TSMC 2001-0603/24061.364
Customer Number: 42717

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Chang et al.

Serial No.: 10/043,863

Filed: 01/10/2002

For: Photoresist Scum for Copper Dual
Damascene Process

§ Attorney Docket: 24061.364
§
§ Confirmation Number: 8427
§
§ Art Unit: 1765
§
§ Examiner: Chen, Kin Chan
§
§ Notice of Allowance: 04/23/2004

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450
MAIL STOP ISSUE FEE

TRANSMITTAL

Dear Sir:

In response to the Notice of Allowance and Issue Fee Due mailed on April 23, 2004, enclosed are the following:

1. Part B - Issue Fee Transmittal (in duplicate);
2. Revocation/New Power of Attorney and Supplemental Sheet (3 pages);
3. "Fee Address" Indication Form (1 page);
4. Check in the amount of \$1330.00; and
5. Return postcard.

The Commissioner is hereby authorized to charge Deposit Account No. 08-1394 for any deficiencies in the enclosed fees. This sheet submitted in duplicate.

Respectfully submitted,

David M. O'Dell
Registration No. 42,044

Date: 7-22-04
HAYNES AND BOONE, LLP
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R80644.1

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents
PO Box 1450, Alexandria, VA 22313-1450

on

7-23-04

Bonnie Boyle
Bonnie E. Boyle